

		<b>Package Material Content Declaration</b>						
<b>Package Description</b>	4-Ball, 2 x 2 Array, 0.40 mm Pitch, Wafer Level Chip Scale Package (WLCSP) with BSC							
<b>Lead Finish</b>	Tin-Silver-Copper (Sn-Ag-Cu)	<b>Package Code / GPC</b>		ECB / GUJ				
<b>J-STD-609 Category</b>	e1	<b>Termination Base Alloy:</b>		Other				
<b>Package Material Declaration</b>								
Material	Substance	CAS #	Weight (mg)	Homogeneous Material		Package		
				Percentage	ppm	Percentage	ppm	
Backside Coating	Silica	Proprietary	0.010	56.5	565000	3.57	35673	
	Epoxy Resin	Proprietary	0.004	21.1	211000	1.33	13322	
	Acrylic Resin	Proprietary	0.004	21.1	211000	1.33	13322	
	Carbon Black	1333-86-4	0.000	1.3	13000	0.08	821	
<b>Sub-Total</b>			<b>0.018</b>	<b>100.0</b>	<b>1000000</b>	<b>6.31</b>	<b>63138</b>	
Integrated Circuit	Silicon (Si)	7440-21-3	0.212	100.0	1000000	74.80	747960	
<b>Sub-Total</b>			<b>0.212</b>	<b>100.0</b>	<b>1000000</b>	<b>74.80</b>	<b>747960</b>	
PI Layer	N-Methyl-2-pyrrolidone	872-50-4	0.002	54.7	547000	0.83	8333	
	Non regulated ingredients	Proprietary	0.002	39.7	397000	0.60	6048	
	3,6,9-Trioxaundecamethylene Dimethacrylate	109-17-1	0.000	5.2	52000	0.08	792	
	Methanol	67-56-1	0.000	0.4	4000	0.01	61	
<b>Sub-Total</b>			<b>0.004</b>	<b>100.0</b>	<b>1000000</b>	<b>1.52</b>	<b>15234</b>	
Redistribution Layer	Copper (Cu)	7440-50-8	0.010	99.1	991000	3.68	36813	
	Titanium (Ti)	7440-32-6	0.000	0.9	9000	0.03	334	
<b>Sub-Total</b>			<b>0.011</b>	<b>100.0</b>	<b>1000000</b>	<b>3.71</b>	<b>37148</b>	
Underbump Metal	Copper (Cu)	7440-50-8	0.006	99.4	994000	2.06	20578	
	Titanium (Ti)	7440-32-6	0.000	0.6	6000	0.01	124	
<b>Sub-Total</b>			<b>0.006</b>	<b>100.0</b>	<b>1000000</b>	<b>2.07</b>	<b>20702</b>	
Solder Ball	Tin (Sn)	7440-31-5	0.031	95.5	955000	11.06	110606	
	Silver (Ag)	7440-22-4	0.001	4.0	40000	0.46	4633	
	Copper (Cu)	7440-50-8	0.000	0.5	5000	0.06	579	
<b>Sub-Total</b>			<b>0.033</b>	<b>100.0</b>	<b>1000000</b>	<b>11.58</b>	<b>115818</b>	
<b>Total</b>			<b>0.284</b>			<b>100.00</b>	<b>1000000</b>	

This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero).

Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.

If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.

Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at <http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/>.

The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.

Microchip Technology Incorporated believes the information in this form concerning substances restricted by RoHS in Microchip Technology Incorporated's semiconductor devices in their original packing materials is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated cannot guarantee the completeness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers. Supplier information is often protected from disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers. Information is provided only as estimates of the average weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not include trace levels of dopants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts.

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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at <http://echa.europa.eu/web/guest/candidate-list-table>.